Transistors

General purpose (dual digital transistors) UMB11N/IMB11A

Features

- Two DTA114Es in a UMT or SMT package.
- Mounting possible with UMT3 or SMT3 automatic mounting machines.
- Transistor elements are independent, eliminating interference.
- 4) Mounting cost and area can be cut in half.

Structure

Epitaxial planar type PNP silicon transistor (Built-in transistor type)

The following characteristics apply to both DTr_1 and DTr_2 .

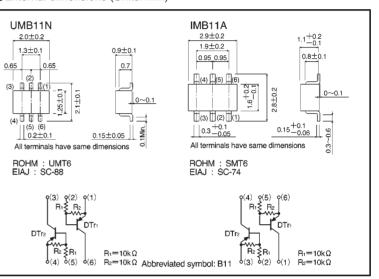
•Absolute maximum ratings (Ta = 25° C)

Parameter		Symbol	Limits	Unit	
Supply voltage		Vcc	-50	V	
Input voltage		Vin	-40	v	
		VIN	10		
Output current		lo	-50	mA	
		IC(Max.)	-100	IIIA	
Power dissipation	UMB11N	Pd	150(TOTAL)	*1 mW	
	IMB11A	FU	300(TOTAL)	*2	
Junction temperature		Tj	150	ĉ	
Storage temperature		Tstg	-55~+150	ů	

*1 120mW per element must not be exceeded.

*2 200mW per element must not be exceeded.

External dimensions (Units: mm)





•Electrical characteristics (Ta = 25° C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Input voltage	VI (off)	-	_	-0.5	V	$V_{CC} = -5V$, Io=-100 μ A
Input voltage	$V_{I \ (on)}$	-3.0	—	_		Vo=-0.3V, lo=-10mA
Output voltage	$V_{O\left(on\right) }$	-	0.1	-0.3	V	lo/li=-10mA/-0.5mA
Input current	h		_	-0.88	mA	V1=-5V
Output current	lo(off)	-	—	-0.5	μA	$V_{CC} = -50V, V_i = 0V$
DC current gain	G	30	_	_	_	$V_0 = -5V$, $I_0 = -5mA$
Transition frequency	fτ	-	250	_	MHz	Vce=10mA, le=-5mA, f=100MHz*
Input resistance	R1	7	10	13	kΩ	_
Resistance ratio	R2/R1	0.8	1	1.2	_	_

* Transition frequency of the device

Packaging specifications

	Packaging type	Taping		
	Code	TN	T110	
Part No.	Basic ordering unit (pieces)	3000	3000	
UMB11N		0	—	
IMB11A			0	

Electrical characteristic curves

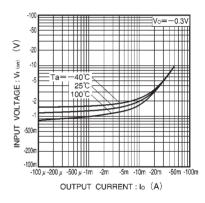


Fig.1 Input voltage vs. output current (ON characteristics)

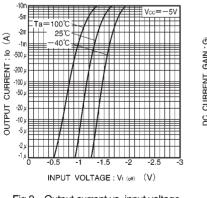


Fig.2 Output current vs. input voltage (OFF characteristics)

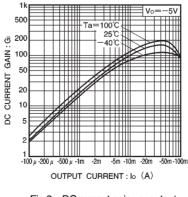


Fig.3 DC current gain vs. output current

